

Title (en)  
Process and device for water jet cutting

Title (de)  
Verfahren und Vorrichtung zum Wasserstrahlschneiden

Title (fr)  
Procédé et dispositif pour le découpage au jet d'eau

Publication  
**EP 1557239 A1 20050727 (DE)**

Application  
**EP 04100247 A 20040123**

Priority  
EP 04100247 A 20040123

Abstract (en)  
To cut through workpieces (5) with a high pressure and focused water jet, containing solid particles, the workpiece is moved by a holder (6-10) as it is cut by the water jet (4) e.g. a pipe is rotated under the water jet. The workpiece is immersed within a water bath (2), where the surface is over the water surface (1), and the jet stream is caught in the bath after passing through the workpiece walls. The water jet head (3) is given at least a two-dimensional movement during cutting.

Abstract (de)  
Die Erfindung betrifft ein Verfahren und eine Vorrichtung zum Wasserstrahlschneiden, bei dem/der das Werkstück 5 durch eine Werkstückhalterung 6 - 10 bewegt und dabei so in einem Wasserbad 2 gehalten wird, dass es zu einem wesentlichen Teil eingetaucht ist. <IMAGE>

IPC 1-7  
**B24C 1/04**

IPC 8 full level  
**B24C 1/04** (2006.01)

CPC (source: EP)  
**B24C 1/045** (2013.01)

Citation (search report)  
• [X] US 5512007 A 19960430 - DE LUCIA FRANK V [US], et al  
• [X] US 5279075 A 19940118 - SAGE COLIN [GB], et al  
• [A] US 4604923 A 19860812 - LINK HELMUT F [DE], et al

Cited by  
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Designated contracting state (EPC)  
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PT RO SE SI SK TR

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